

## Press Release, 17 March 2010

### Paper on Long Wave Infrared Bolometer and Wafer Bonding to be presented at SPIE DSS Conference April 6, 2010

[Sensoror Technologies](#) is developing un-cooled infrared sensors (FPA) for thermal imaging cameras. Sensoror will present a paper at the upcoming [SPIE Defense, Security and Sensing](#) (DSS) discussing some of its achievements in the area of design and fabrication. The conference will take place April 5<sup>th</sup> to 9<sup>th</sup> in Orlando, FL, US.

The talk is entitled “High-performance long wave infrared bolometer fabricated by wafer bonding”. It will be held by Dr. Adriana Lapadatu, Senior Engineer at Sensoror. According to Dr. Lapadatu; “A novel microbolometer with peak responsivity in the long wave infrared region of the electromagnetic radiation is under development. It is a focal plane array of pixels with a 25µm pitch, based on monocrystalline Si/SiGe quantum wells as IR sensitive material. The novelty of the proposed 3D process integration comes from the choice of several of the materials and key processes involved, which allow a high fill factor and provide improved transmission/absorption properties. Together with the high TCR and low 1/f noise provided by the thermistor material, they will lead to bolometer performances beyond those of existing devices.”

#### About Sensoror Technologies AS

Sensoror is a global leader in high precision MEMS technology; designing and manufacturing advanced, integrated gyro and pressure sensors for harsh environments. Based on a continuous MEMS activity since 1965, Sensoror pioneered the introduction of MEMS accelerometers and gyros to the automotive market and also became the leading supplier of tire pressure sensors.

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